RAM Keep-Alive

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A COPSTM application is a small scale computer system and the design of a power shut-down is not trivial. During the time that power is available, but out of the designed operating range, the system must be prevented from doing anything to harm protected data. This will typically involve some type of external protection of timing circuit.

There is an option on the COP420, 420L, and 410L parts called "RAM Keep-Alive" that provides a separate power supply to the RAM area of the chip via the CKO pin. The application of power to the RAM while the remainder of the chip has been powered down via V_{CC} will keep the RAM "alive".

However, the integrity of data in the RAM is not only a function of power but is also influenced by transient conditions as power is removed and reapplied. During power-on, the Power On Reset (POR) circuit will keep transients from causing changes in the RAM states. The condition of power loss will have some probability of data change if external control is not used.

At some point below the minimum operating voltage certain gates will no longer respond properly while others may still be functional until a much lower voltage. During this transition time any false signal could cause a false write to one or more cells. Another effect could be to turn on multiple address select lines causing data destruction.

Testing the rate of data change is very difficult because it must be done on a statistical basis with many turn/on-turn/ off cycles. Two factors have a major bearing on the numbers derived by testing. One is to call any change in a related data block a failure, even though more than one bit in that block may have changed (this latter case may well be due to the "address select mode"). The second factor is that without massive instrumentation it is impossible to examine the data after each power cycle. Indeed, to do so might have caused errors!

By running the power cycle for a period of time and then looking for changes, one could overlook multiple changes thus reducing the error rate. This has been minimized by more frequent checking which indicates that the errors are spread out randomly over time.

With a power supply that drops from 4.5 to 2V in approximately 100 ms, the drop-out rate is 1 in 5k to 6k power cycles. Reducing the voltage fall time will cause an improvement in the number of cycles per drop-out. This will reach a limit condition of a very high number (1 per 1 million?) when the power falls within one instruction cycle (4–10 μs for the 420, 15–40 μs for the "L" parts). Attaining very rapid fall time may cause problems due to the lack of decoupling/bypass capacitance. By inserting an electronic switch between the regulator and V_{CC} of the COP chip one might be able to meet this type of fall time. By implication some type of sensing is required to cause the switching.

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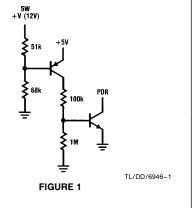
The desirable approach is to force the COP reset input to zero before the voltage falls below 4.5V. This provides a drop out rate of approximately 1 in 50k for the "L" parts and 1 in 100k for the 420. By also stopping the clock of the "L" parts they can achieve a drop-out rate similar to the 420. While not perfect, the number of cycles between data error should be considered with respect to the needs of the application.

The external circuitry to control the chip during the power transition has several implementations each one being a function of the application. The simplest hardware is found in a battery powered (automotive) application. The circuit must sense that the switched 12V is falling (e.g., at some value much below 12V and still greater than 5V). This can be done by using the unswitched 12V as a reference for a divider to a nominal voltage of 8V. As the switched 12V drops below the reference a detector will turn on a clamp transistor to a series switch, the POR, and/or the clock circuit (*Figure 1*). It should be noted that this draws current during the absence of the switched 12V circuit.

In non-automotive usage a similar circuit can be used where there is a stable reference voltage available to use with the comparator/clamp. Thus a 3.6V rechargable Ni-Cad battery could be used as the reference voltage and V_{RAM} if the appropriate divider is used to level shift to this operating range.

In AC line-powered applications, a similar method could be used with the raw DC being sensed for drop. Another method would be to sense that the line had missed 2–3 cycles either by means of a charge pump or peak detection technique. This will provide the signal to turn on the clamp. One must make this faster than the time to discharge the output capacitance of the power supply, thus assuring that the clamp has performed its function before the supply falls below spec value.

In conclusion, to protect the data stored in RAM during power-off cycle, the POR should go low before the V_{CC} power drops below spec and come up after V_{CC} is within spec. The first item must be handled with an external circuit like *Figure 1* and the latter by an RC per the data sheet.





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